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(54) **ON-CHIP SHIELDED DEVICE**

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(71) Applicant: **NXP B.V.**, Eindhoven (NL)

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(72) Inventors: **Philipp Franz Freidl**, Weurt (NL);  
**Mustafa Acar**, Eindhoven (NL);  
**Antonius Hendrikus Jozef Kamphuis**,  
Eindhoven (NL); **Erik Daniel Björk**,  
Sollentuna (SE); **Konstantinos**  
**Giannakidis**, Eindhoven (NL); **Jan**  
**Willem Bergman**, Veghel (NL); **Rajesh**  
**Mandamparambil**, Eindhoven (NL);  
**Paul Mattheijssen**, Boxtel (NL)

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(57) **ABSTRACT**

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One example discloses an on-chip shielded device, including: a planar structure including a substrate and a passivation layer; an electrical component formed within the substrate and coupled to an input signal path and an output signal path; a first shielding element positioned above the electrical component and the passivation layer; and a second shielding element positioned above the electrical component, the passivation layer and the first shielding element.

